Wiring, Printed - Component

COMPANY

SHING TECH ELECTRONICS CO LTD
303 SEC 2 NANSHAN RD
LUZHU TOWNSHIP
TAOYUAN HSIEN, 338 Taiwan

E248803

Type	Cond Width Min mm	Cond Width Min Edge mm	Cond Thk mic	SS/ DS/ DSO	Max Area Diam mm	Report date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp °C	Assembly Solder Process Cycles	Solder Limits °C	Solder Limits sec	Max Oper Temp °C	Flame Class	Meets UL796 DSR	CTI
Multilayer metal base printed wiring boards															
AL02	0.1	0.2	34 Int:68	SS	50.8	No	-	-	-	260	10	140	V-0	All	1
Multilayer printed wiring boards															
AM01	1.6	4.8	17	DS	25.4	No	-	-	-	260	10	130	V-0	All	-
BM01	0.075	0.10	17 Int:68	DS	25.4	No	-	-	-	260	10	105	V-0	All	-
BM02	0.12	0.12	17 Int:27	DS	25.4	No	-	-	-	260	10	130	V-0	All	-
FM01	0.075	0.075	12 Int:68	DS	50.8	No	-	-	-	260	10	130	V-0	All	3
FM02 (ASP 1)	0.075	0.075	12 Int:68	DS	50.8	Yes	Yes	260	6	-	-	130	V-0	All	*
GM01	0.10	0.10	12 Int:102	DS	25.4	No	-	-	-	260	10	130	V-0	All	2
GM01A	0.075	0.075	12 Int:102	DS	25.4	No	-	-	-	260	10	130	V-0	All	4
HM01(a)	0.10	0.10	12 Int:210	DS	50.8	No	-	-	-	260	10	130	V-0	All	3
HM02 (ASP 1)	0.075	0.75	12 Int:102	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
HM02A (ASP 1)	0.075	0.075	12 Int:102	DS	12.7	Yes	Yes	260	3	-	-	130	V-0	All	*

RM01	0.075	0.075	17 Int:102	DS	50.8	No	-	-	-	260	10	130	V-0	All	*
Single layer metal base printed wiring boards															
AL01	0.1	0.2	34	SS	50.8	No	-	-	-	260	10	140	V-0	All	0
AL01A	0.1	0.1	17	SS	50.8	No	-	-	-	260	10	130	V-0	All	0
AL01B	0.1	0.1	34	SS	50.8	No	-	-	-	260	10	105	V-0	All	2
AL03	0.10	0.10	17	DS	50.8	No	-	-	-	260	10	130	V-0	-	0
Single layer printed wiring boards															
AD01	1.6	4.8	17	DS	25.4	No	-	-	-	260	10	130	V-0	All	-
BD01	0.075	0.1	17	DS	25.4	No	-	-	-	260	10	105	V-0	All	-
BD02	0.12	0.12	17	DS	25.4	No	-	-	-	260	10	130	V-0	All	-
FD01	0.075	0.075	12	DS	50.8	No	-	-	-	260	10	130	V-0	All	3
GD01	0.10	0.10	12	DS	25.4	No	-	-	-	260	10	130	V-0	All	2
GD01A	0.075	0.075	12	DS	25.4	No	-	-	-	260	10	130	V-0	All	4
HD01(a)	0.10	0.10	12	DS	50.8	No	-	-	-	260	10	130	V-0	All	3
HD02 (ASP 1)	0.10	0.10	12	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
HD02A (ASP 1)	0.10	0.10	12	DS	12.7	Yes	Yes	260	3	-	-	130	V-0	All	*
RD01	0.075	0.075	17	DS	50.8	No	-	-	-	260	10	130	V-0	All	0

* - CTI marking is optional and may be marked on the printed wiring board.

(a) - For Types HD01& HM01: Min. Cond. Width = 0.10 mm/ Edge Cond. Width = 0.10 mm for External Cu Thk = 12 ~ 102 mic; Min. Cond. Width = 0.40 mm/ Edge Cond. Width = 0.40 mm for External Cu Thk = 102 ~ 210 mic.

(ASP 1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

Marking: Company name or trademark NCAB _T6_ , SW or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2023-12-14
